

BF824,235 Datasheet



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DiGi Electronics Part Number BF824,235-DG

Manufacturer Nexperia USA Inc.

Manufacturer Product Number BF824,235

Description TRANS PNP 30V 0.025A TO236AB

Detailed Description Bipolar (BJT) Transistor PNP 30 V 25 mA 450MHz 25

0 mW Surface Mount TO-236AB



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Purchase and inquiry

Manufacturer Product Number:	Manufacturer:
BF824,235	Nexperia USA Inc.
Series:	Product Status:
	Active
Transistor Type:	Current - Collector (Ic) (Max):
PNP	25 mA
Voltage - Collector Emitter Breakdown (Max):	Vce Saturation (Max) @ lb, lc:
30 V	
Current - Collector Cutoff (Max):	DC Current Gain (hFE) (Min) @ Ic, Vce:
50nA (ICBO)	25 @ 4mA, 10V
Power - Max:	Frequency - Transition:
250 mW	450MHz
Operating Temperature:	Grade:
150°C (TJ)	Automotive
Qualification:	Mounting Type:
AEC-Q101	Surface Mount
Package / Case:	Supplier Device Package:
TO-236-3, SC-59, SOT-23-3	TO-236AB
Base Product Number:	
BF824	

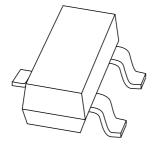
Environmental & Export classification

8541.21.0075

RoHS Status:	Moisture Sensitivity Level (MSL):
ROHS3 Compliant	1 (Unlimited)
REACH Status:	ECCN:
REACH Unaffected	EAR99
HTSUS:	

DISCRETE SEMICONDUCTORS

DATA SHEET



BF824PNP medium frequency transistor

Product data sheet Supersedes data of 1999 Apr 15 2004 Jan 16



PNP medium frequency transistor

BF824

FEATURES

- Low current (max. 25 mA)
- Low voltage (max. 30 V).

APPLICATIONS

• RF stages in FM front-ends in common base configuration.

DESCRIPTION

PNP medium frequency transistor in a SOT23 plastic package.

MARKING

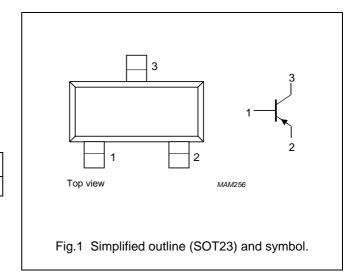
TYPE NUMBER	MARKING CODE(1)
BF824	F8*

Note

* = p : Made in Hong Kong.
 * = t : Made in Malaysia.
 * = W : Made in China.

PINNING

PIN	DESCRIPTION
1	base
2	emitter
3	collector



ORDERING INFORMATION

TYPE NUMBER	PACKAGE					
TIPE NOWIBER	NAME	DESCRIPTION	VERSION			
BF824	-	plastic surface mounted package; 3 leads	SOT23			

PNP medium frequency transistor

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LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{CBO}	collector-base voltage	open emitter	_	-30	V
V_{CEO}	collector-emitter voltage	open base	-	-30	V
V _{EBO}	emitter-base voltage	open collector	_	-4	V
I _C	collector current (DC)		_	-25	mA
I _{CM}	peak collector current		-	-25	mA
P _{tot}	total power dissipation	T _{amb} ≤ 25 °C; note 1	_	250	mW
T _{stg}	storage temperature		-65	+150	°C
Tj	junction temperature		_	150	°C
T _{amb}	operating ambient temperature		-65	+150	°C

Note

1. Transistor mounted on an FR4 printed-circuit board.

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th(j-a)}	thermal resistance from junction to ambient	note 1	500	K/W

Note

1. Transistor mounted on an FR4 printed-circuit board.

CHARACTERISTICS

 $T_j = 25$ °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I _{CBO}	collector cut-off current	$I_E = 0; V_{CB} = -30 \text{ V}$	-	_	-50	nA
I _{EBO}	emitter cut-off current	$I_C = 0; V_{EB} = -4 V$	_	_	-100	nA
h _{FE}	DC current gain	$I_C = -1 \text{ mA}; V_{CE} = -10 \text{ V}$	25	45	_	
		$I_C = -4 \text{ mA}; V_{CE} = -10 \text{ V}$	25	50	_	
V_{BE}	base-emitter voltage	$I_C = -4 \text{ mA}; V_{CE} = -10 \text{ V}$	_	_	-900	mV
C_{re}	feedback capacitance	$I_C = 0$; $V_{CE} = -10 \text{ V}$; $f = 1 \text{ MHz}$	_	_	0.3	pF
f _T	transition frequency	$V_{CE} = -10 \text{ V}; f = 100 \text{ MHz}$				
		$I_C = -1 \text{ mA}$	250	350	_	MHz
		$I_C = -4 \text{ mA}$	400	450	_	MHz
		$I_C = -8 \text{ mA}$	390	440	_	MHz

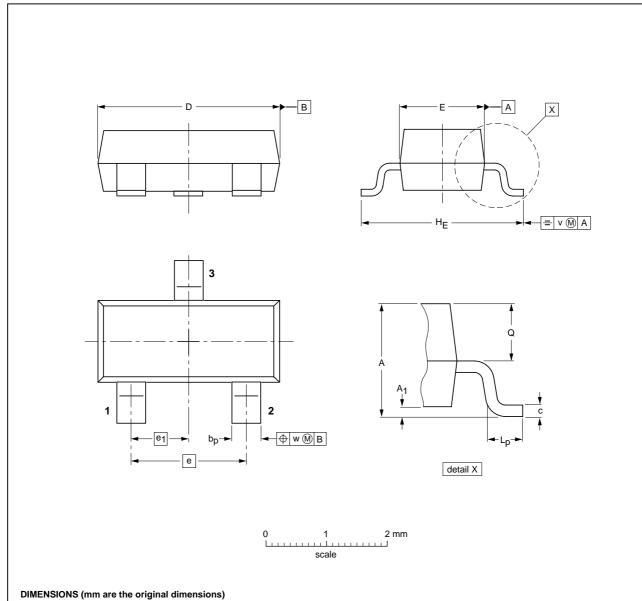
PNP medium frequency transistor

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PACKAGE OUTLINE



SOT23



UNIT	Α	A ₁ max.	bp	С	D	E	е	e ₁	H _E	Lp	Q	v	w
mm	1.1	0.1	0.48	0.15	3.0	1.4	1.9	0.95	2.5	0.45	0.55	0.2	0.1

OUTLINE		REFER	EUROPEAN	ISSUE DATE			
VERSION	IEC	JEDEC JEITA			PROJECTION	ISSUE DATE	
SOT23		TO-236AB				-04-11-04- 06-03-16	

PNP medium frequency transistor

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DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

Notes

- 1. Please consult the most recently issued document before initiating or completing a design.
- 2. The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

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Customer notification

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

Contact information

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